



SOD-123FL Plastic-Encapsulate Diodes

DSS22 THRU DSS210 Schottky Rectifier Diodes

Features

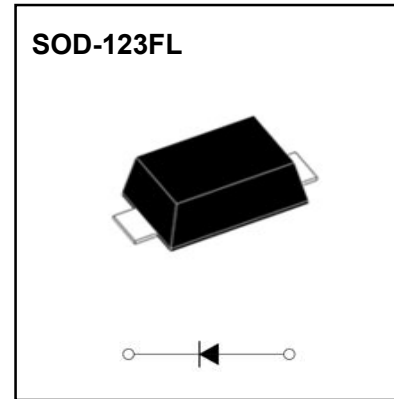
- $I_{F(AV)}$ 2A
- V_{RRM} 20V-100V
- High surge current capability
- Polarity: Color band denotes cathode

Applications

- Rectifier

Marking

- DSS22-DSS210 : S22-S210



Limiting Values (Absolute Maximum Rating)

Item	Symbol	Unit	Test Conditions	DSS						
				22	23	24	25	26	28	210
Repetitive Peak Reverse Voltage	V_{RRM}	V		20	30	40	50	60	80	100
Maximum RMS Voltage	V_{RMS}	V		14	21	28	35	42	56	70
Maximum DC Blocking Voltage	V_{DC}	V		20	30	40	50	60	80	100
Average Forward Current	$I_{F(AV)}$	A	60Hz Half-sine wave, Resistance load, $T_L=(Fig.1)$	2.0						
Surge(Non-repetitive)Forward Current	I_{FSM}	A	60Hz Half-sine wave, 1 cycle, $T_a=25^\circ C$	40						
Junction Temperature	T_J	$^\circ C$		-55~+125			-55~+150			
Storage Temperature	T_{STG}	$^\circ C$		-55 ~ +150						

Electrical Characteristics (T=25 °C Unless otherwise specified)

Item	Symbol	Unit	Test Condition	DSS						
				22	23	24	25	26	28	210
Peak Forward Voltage	V_{FM}	V	$I_{FM}=2.0A$	0.55			0.70		0.85	
Peak Reverse Current	I_{RRM1}	mA	$V_{RM}=V_{RRM}$	$T_a=25^\circ C$			0.5		0.1	
	I_{RRM2}			$T_a=100^\circ C$			10		5.0	
Thermal Resistance(Typical)	$R_{\theta J-A}$	$^\circ C/W$	Between junction and ambient	75						
	$R_{\theta J-L}$		Between junction and terminal	17						

Notes:

Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.2" x 0.2" (5.0 mm x 5.0 mm) copper pad areas

Typical Characteristics

FIG.1: FORWARD CURRENT DERATING CURVE

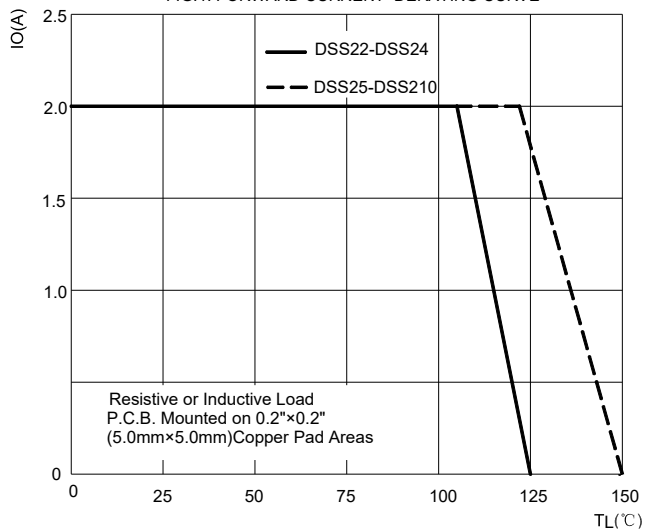


FIG.2: MAXIMUM NON-REPETITIVE FORWARD URGE CURRENT

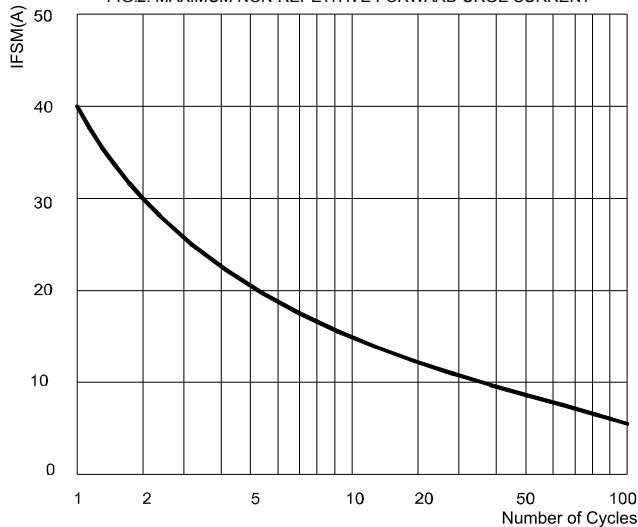


FIG.3: TYPICAL FORWARD CHARACTERISTICS

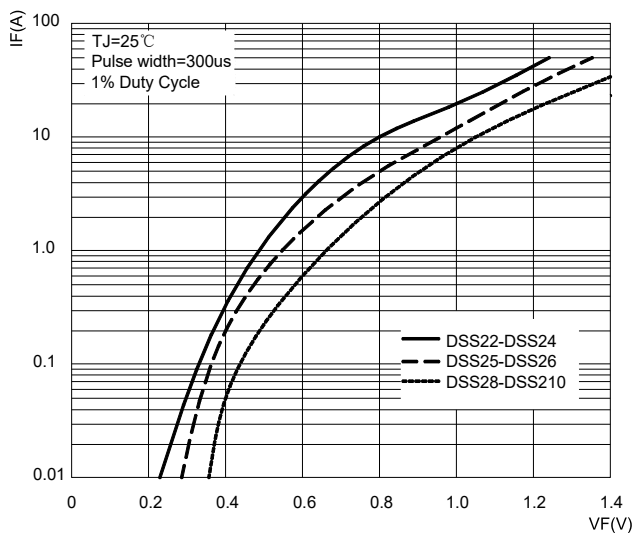
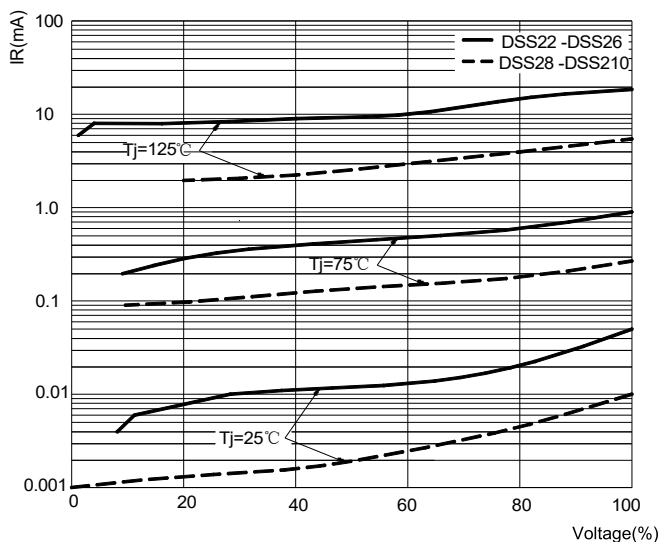
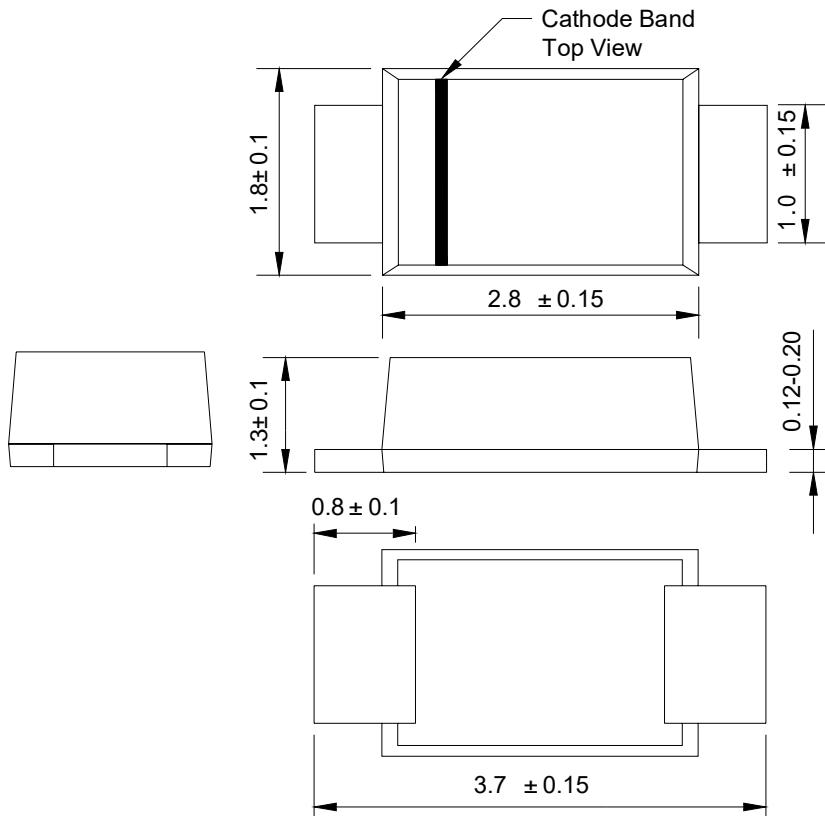


FIG.4: TYPICAL REVERSE CHARACTERISTICS

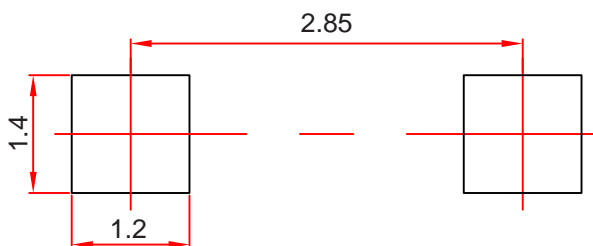


SOD-123FL Package Outline Dimensions



Dimensions in millimeters

SOD-123FL Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05 mm.
3. The pad layout is for reference purposes only.

NOTICE

JSCJ reserves the right to make modifications, enhancements, improvements, corrections or other changes without further notice to any product herein. JSCJ does not assume any liability arising out of the application or use of any product described herein.

Reel Taping Specifications For Surface Mount Devices-SOD-123FL

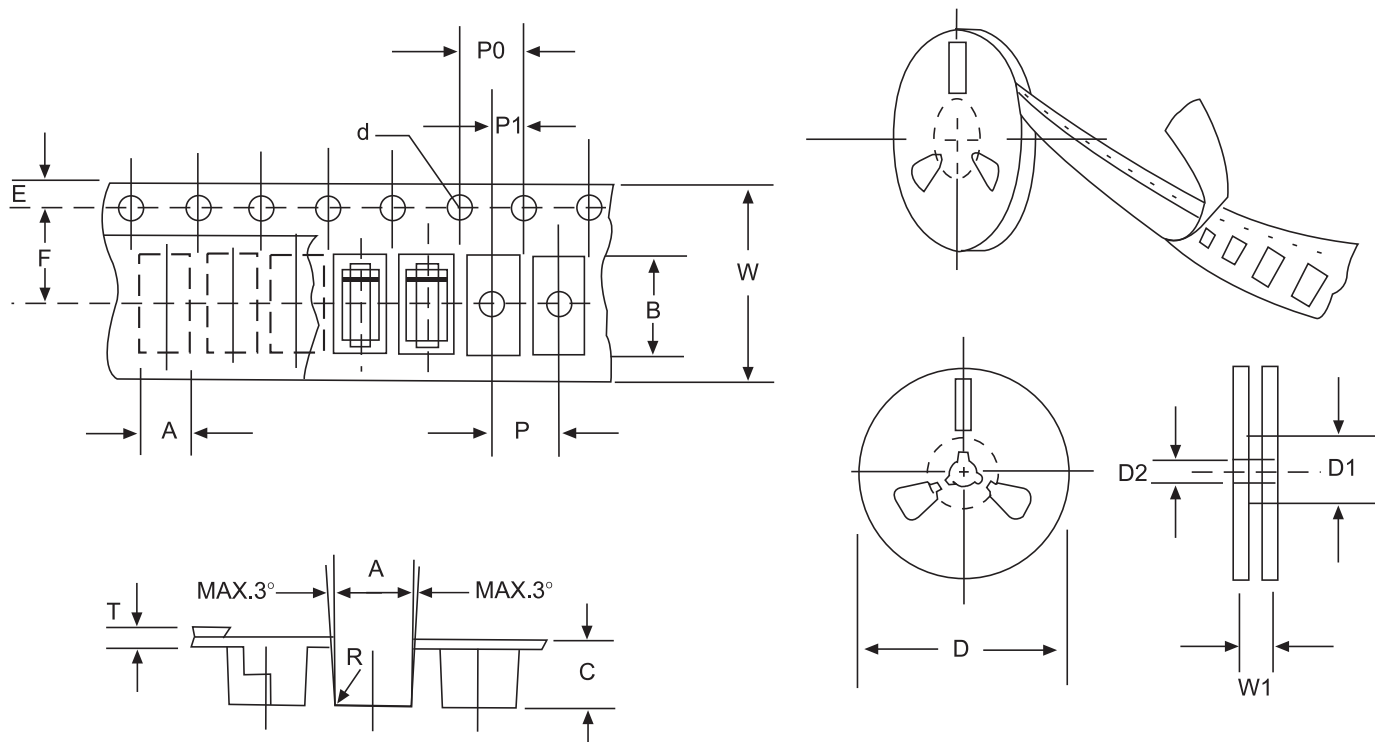


FIG: CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING

ITEM	SYMBOL	SOD-123FLmm(inch)
Carrier width	A	2.05±0.1(0.081±0.004)
Carrier length	B	3.95±0.1(0.156±0.004)
Carrier depth	C	1.45±0.1(0.057±0.004)
Sprocket hole	d	1.55±0.05(0.061±0.002)
Reel outside diameter	D	178±2.0(7.0±0.079)
Reel inner diameter	D1	54±1.0(2.13±0.039)
Feed hole diameter	D2	13±0.5(0.512±0.020)
Sprocket hole position	E	1.75±0.1(0.069±0.004)
Punch hole position	F	3.50±0.1(0.138±0.002)
Punch hole pitch	P	4.0±0.1(0.157±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Total tape thickness	T	0.21±0.025(0.008±0.010)
Tape width	W	8.0±0.2(0.315±0.008)
Reel width	W1	10.0±2.0(0.394±0.079)

NOTE: Devices are packed in accordance with EIA standard RS-481-A and specification given above.